

Product Change Notification - JAON-29WASP224

Date:

27 Jan 2020

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3703 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of the 35.5K wafer technology available in 64L VQFN packages at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of the 35.5K wafer technology available in 64L VQFN packages at NSEB assembly site.

Pre-Change:

Assembled using gold (Au) bond wire, 8200T die attach and G770HCD molding compound material.

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited / NSEB	UTAC Thai Limited / NSEB
Wire material	Au	CuPdAu
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	EFTEC 64T	EFTEC 64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD molding compound material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 27, 2020(date code: 2009)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and



post change parts.

Time Table Summary:

Workweek	March 2019				-->	January 2020					February 2020				
	10	11	12	13		01	02	03	04	05	06	07	08	09	10
Initial PCN Issue Date	X														
Qual Report Availability												X			
Final PCN Issue Date												X			
Estimated Implementation Date															X

Method to Identify Change:

Traceability code.

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

March 4, 2019: Issued initial notification.

January 27, 2020: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 27, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-29WASP224_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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